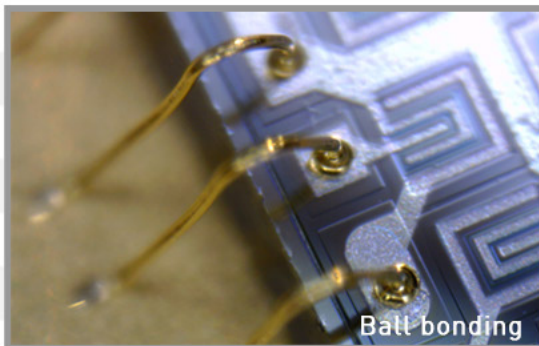


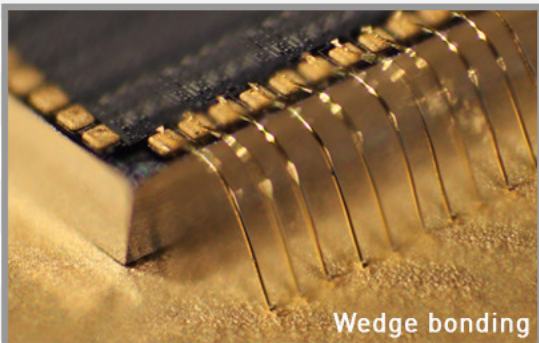


# HB10 Wedge & Ball Bonder

Motorized Z- Axis



Ball bonding



Wedge bonding

- + Wedge, Ball, Bump and Ribbon bonding
- + 17 $\mu$  to 75 $\mu$  Wire and 25 $\mu$  x 250 $\mu$  Ribbon
- + 6,5" TFT Touch Screen
- + Deep-Access Wedge 16mm / Ball 13mm
- + Bond Arm Length 165mm
- + 100 Program Storage Capacities
- + Motorized Z-Axis
- + USB Backup
- + Electronic Ball Size Control

- + Pick & Place Option
- + Pull Tester Option
- + Copper Bonding Option

# HB10 Thermosonic Wire Bonder for Wedge & Ball Bonding

The HB10 is a **Bench Top Size Wire Bonder**, ideal for laboratories, pilot and small scale production lines. **One Bond Head** for bonding in Ball/Wedge or Wedge/Wedge bonding mode. Only tool change necessary. Easy operation with **TFT Touch Screen**, direct access and simple adjustment of all bond parameters.

## Technical Specifications

Bonding Methode	Wedge-Wedge, Ball-Wedge, Ribbon- & Bumb- bonding
Gold wire diameter	17 - 75 $\mu$ ( 0,7 - 3 mil )
Aluminium wire diameter	17 - 75 $\mu$ ( 0,7 - 3 mil )
Ribbon size	max. 25 x 250 $\mu$ ( 1x 8 mil)
Ultrasonic system	63,3 kHz Transducer PLL Control
Ultrasonic power	0 - 10 Watt Output
Bond time	0 - 10 sec.
Bond force	5 - 150 cNm (350cNm option)
Bonding tool	1,58 $\emptyset$ 19 mm length (0,0624" x 0,750")
Motorised Wire Spool	50,8 mm ( 2" )
Wire termination	Bond Head Tear / Clamp Tear
Wire feed angle	90°
Clamp movement	Motorized, Up / Down
Ball size control	Electronic
Motorized Z travel	17 mm (0,67")
Throat depth	165 mm ( 6,7" )
Fine Table motion	10 mm (0,4 ")
Mouse ratio	6:1
Temperature controller	up to 250°C +/- 1°C
Electrical Requirements	100 - 240V +/- 10% 50/60 Hz 10A max.
Physical Dimensions	680 (27") x 640 (25") x 490mm (19")
Weight	Net 42 kg
Industry Standards	CE standards

## Accessories:



TPT Wire Bonder GmbH & Co.KG

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Specifications are subject to change without prior notice